

## NEWS RELEASE

Shanghai, March 09, 2016

### **Heraeus Electronics to Participate in Global Semiconductor Forum, March 9-11, 2016**

**Company to share its latest advancements packaging materials to improve performance in micro and power electronics.**

Heraeus Electronics, a leading provider of materials solutions for the semiconductor and communications electronics industries, will sponsor the Welcome Dinner of the Global Semiconductor Forum (GSF), which takes place Wednesday, March 9<sup>th</sup> through Friday, March 11<sup>th</sup>, 2016 at the Shanghai Marriott Hotel City Centre. The three-day event, which encompasses the end-to-end value chain of electronics development and production, gives technology leaders from around the world the opportunity to network with peers, discuss issues and discover some of the latest innovations in the semiconductor industry.

On Friday, March 11<sup>th</sup>, as part of the world-class panel of presenters and subject matter experts, Dr. Frank Stietz, President of Heraeus Electronics, will share his insights on the important role packaging materials will play in elevating the performance and functionality of micro and power electronics. His technical presentation will include updates on the promising R&D work that Heraeus Electronics has conducted to create new materials for:

- highly integrated devices
- new materials for high power electronics and thermally demanding applications
- and Materials Systems and Matched Materials for power electronics

Commenting on his upcoming presentation, Dr. Stietz said, "Raising performance standards is a challenge for the entire semiconductor industry. We believe that the key is systems materials, which is why we are excited to share updates on our progress creating even higher-performing materials for our customers. It means a trio of benefits for micro and power electronics companies: greater performance, improved functionality and reliability and the ability to accelerate innovation."

#### **About Heraeus**

Heraeus, the technology group headquartered in Hanau, Germany, is a leading international family-owned company formed in 1851. With expertise, a focus on innovations, operational excellence and an entrepreneurial leadership, we strive to continuously improve our business performance. We create high-quality solutions for our clients and strengthen their

competitiveness in the long term by combining material expertise with technological know-how. Our ideas are focused on themes such as the environment, energy, health, mobility and industrial applications. Our portfolio ranges from components to coordinated material systems which are used in a wide variety of industries, including the steel, electronics, chemical, automotive and telecommunications industries. In the 2014 financial year, Heraeus generated product revenues of €3.4 bn and precious metal revenues of €12.2bn euros. With around 12,600 employees worldwide in more than 100 subsidiaries in 38 countries, Heraeus holds a leading position in its global markets.

#### **About Heraeus Electronics**

Heraeus Electronics - a Global Business Unit of the Heraeus Group - is one of the leading manufacturers of materials for the packaging of integrated circuits in the electronics industry. The company deals with sophisticated material solutions for semiconductor and automotive industry, consumer goods, energy, industry electronics as well as communications and telecommunications. Core competences include bonding wires, assembly materials, thick film pastes as well as roll clad strips and substrates.

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